



BOARD CHARACTERISTICS

Copper Layer Count:	6	Board Thickness:	1.6000 mm
Board overall dimensions:	78.0000 mm x 138.0000 mm		
Min track/spacing:	0.2032 mm / 0.2032 mm	Min hole diameter:	0.1000 mm
Copper Finish:	Immersion gold	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Black	1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	White	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	core	Polyimide	0.274 mm		3.2	0.004
In1.Cu	copper		0.035 mm		1	0
Dielectric 2	prepreg	Polyimide	0.274 mm		3.2	0.004
In2.Cu	copper		0.035 mm		1	0
Dielectric 3	core	Polyimide	0.274 mm		3.2	0.004
In3.Cu	copper		0.035 mm		1	0
Dielectric 4	prepreg	Polyimide	0.274 mm		3.2	0.004
In4.Cu	copper		0.035 mm		1	0
Dielectric 5	core	Polyimide	0.274 mm		3.2	0.004
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	White	3.3	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Black	1	0

NOTES:
D101-D108 are mounted upside-down.
Assemble with leaded solder.

C. Kornowski
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Sheet:
File: backplane.kicad_pcb

Title: backplane	
Size: A	Date: 2022-05-11
KiCad E.D.A. kicad (6.0.5)	Rev: C
	Id: 1/1

